

An Editorial Board Update

Today, the Editorial Board is composed of twelve associate editors from six different countries. These individuals were selected as experts from a number of different areas and help ensure the quality and relevance of the content that we publish. Without these dedicated people the Journal would not be possible. Therefore it is my pleasure to recognize our two newest editorial board members: Dr. Bruce Romenesko and Dr. Gangqiang Wang.

Dr. Romenesko joined the editorial board effective 4th quarter 2006. He has been in the microelectronics field with the Johns Hopkins University Applied Physics Laboratory since 1979. During this time he has held several leadership positions in IMAPS, including President in 2005. Also having served on the Editorial Board in the past, he brings a wealth of knowledge and experience in materials, packaging and reliability.

Dr. Gangqiang (Victor) Wang is the Director of Device Processing at EmiSense, a subsidiary of Ceramatec, Inc. in Salt Lake City, Utah. He currently is working on the development of ceramic based sensors for automotive applications with over fifteen years of experience in electronic materials and electronic packaging.

Both of these individuals bring tremendous experience and expertise to the editorial board and I am honored to serve with them.

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